



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

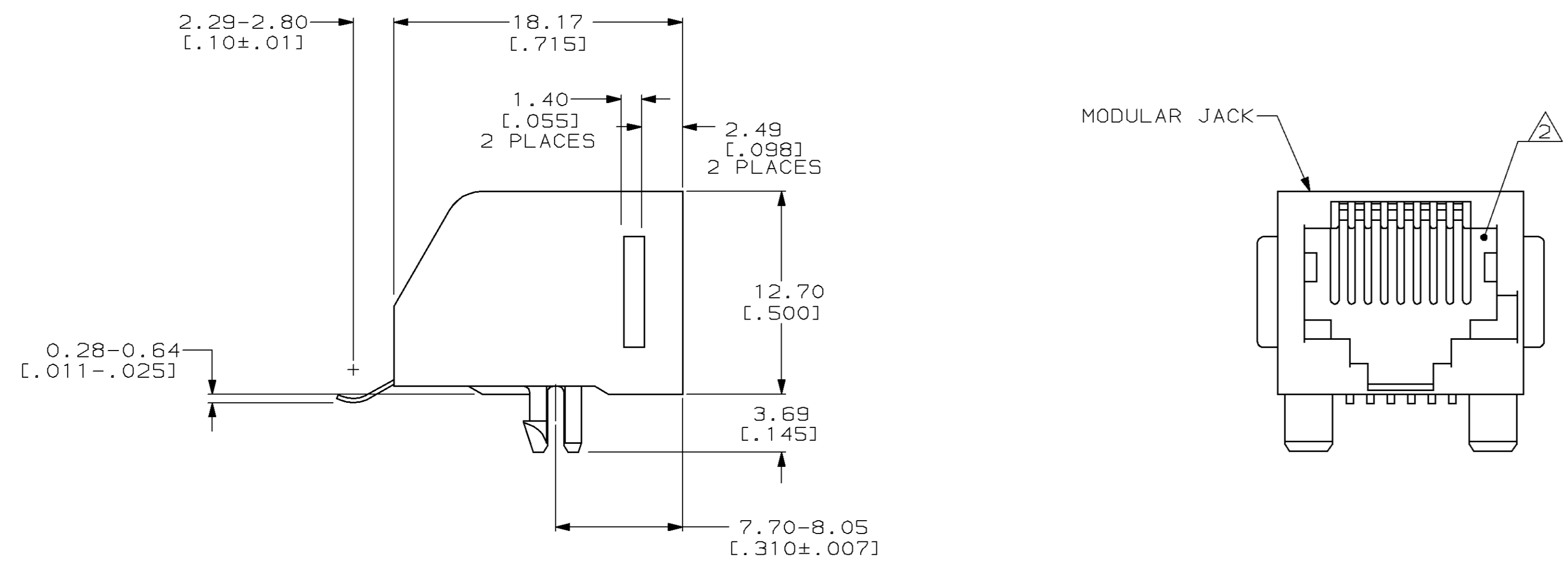
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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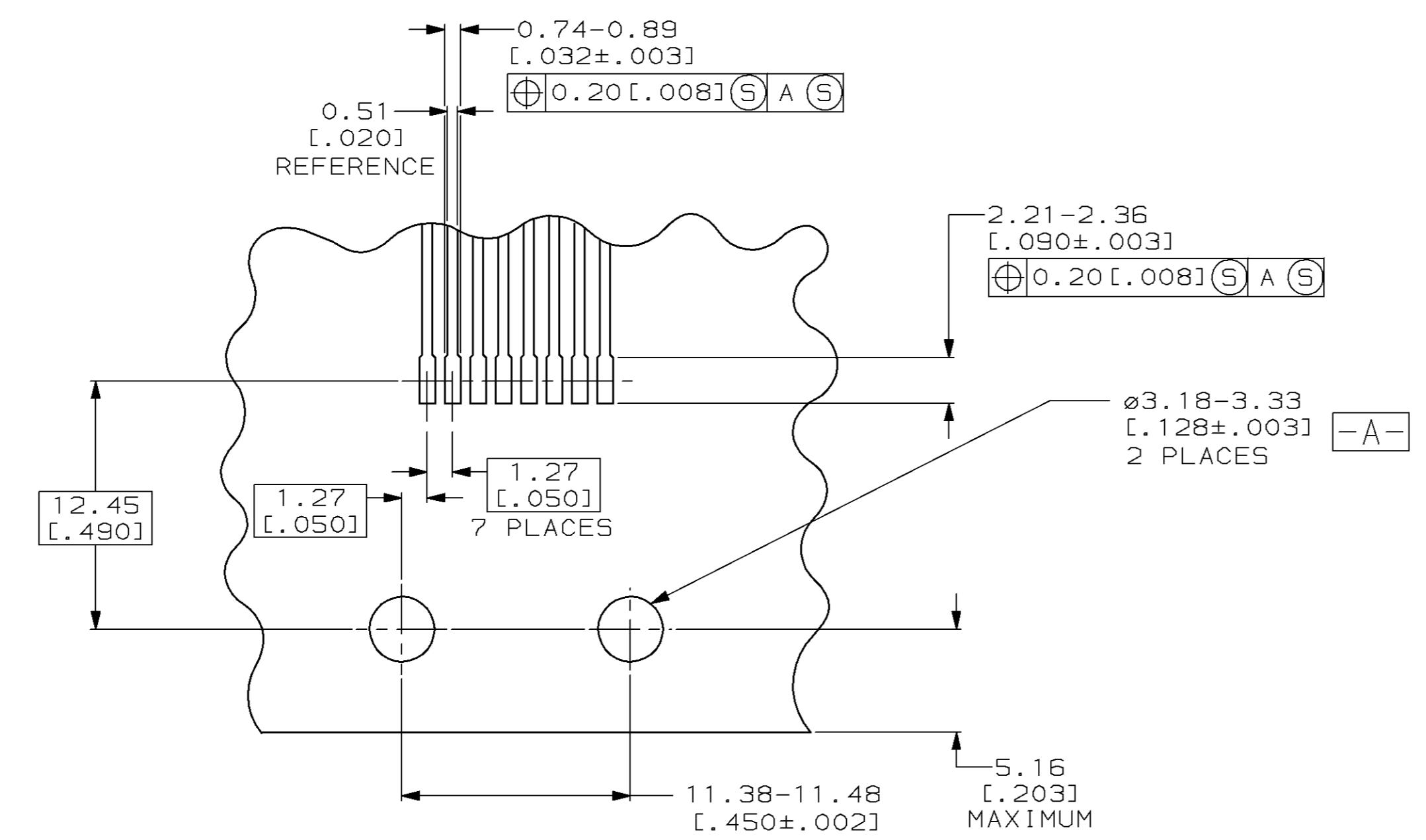
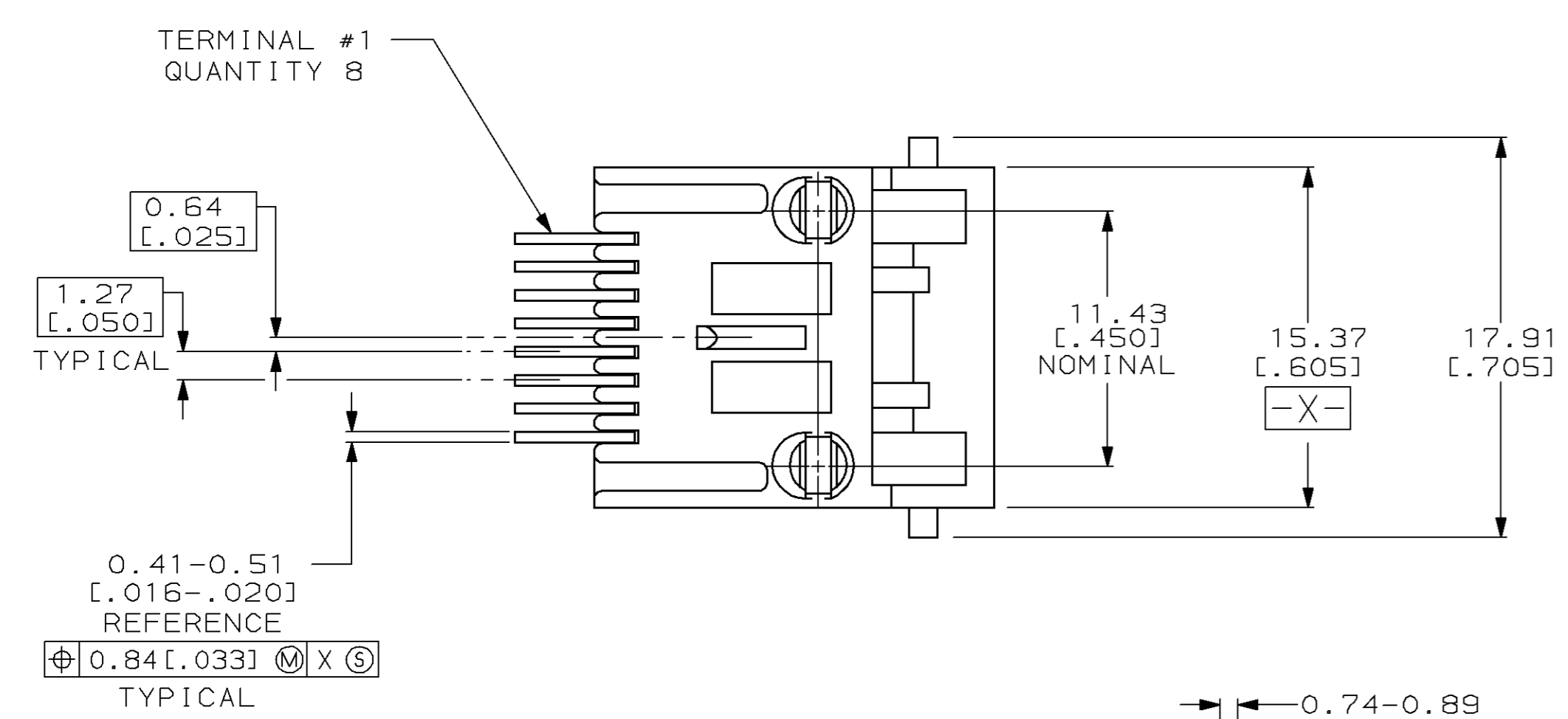
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



| LOC | | DIST | | REV | | ZONE | | LTR | | REVISIONS | | DATE | APPD |
|-----|----|------|---|-----|--|------|--|-----|--|-----------|----------------------|---------|-------|
| AA | 22 | P | F | | | | | | | | REV; EC 0502-0711-97 | 23OCT97 | 05 EL |



- 1. MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 V0, BLACK.
 TERMINAL - 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE.
- 2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- 4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.

| | | | | | | | |
|-------------------------------------------------------------------------------|--|---------------------------|--|-------------------------------------------------------------------------------------------------------------|-----------------|---------------------|--|
| DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON: | | DR 9-28-95 D. STRAUSSER | | 8 | | 555078-1 | |
| 2 PLC DEC ± - | | CHK 10-17-95 N. JONES | | NUMBER OF TERMINALS | | PART NO | |
| 3 PLC DEC ± - | | APPD 10-23-95 J. TONEY | | AMP Incorporated Harrisburg, PA 17105-3608 | | | |
| ANGLES ± - | | APPD 10-24-95 H. MCGRATH | | | | | |
| MATERIAL | | PRODUCT SPEC 108-1163 | | NAME MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT, KEYED, WITH PANEL STOPS | | | |
| FINISH | | APPLICATION SPEC 114-6040 | | SIZE D | CAGE CODE 00779 | DRAWING NO C=555078 | |
| WEIGHT - | | SCALE 4:1 | | SHEET 1 OF 1 | | CUSTOMER DRAWING | |